

K643-VB Datasheet

N-Channel 600V (D-S) Super Junction MOSFET

PRODUCT SUMMARY

V_{DS} (V) at T_J max.	650	
$R_{DS(on)}$ at 25 °C (Ω)	$V_{GS} = 10$ V	0.38
Q_g max. (nC)	38	
Q_{gs} (nC)	4	
Q_{gd} (nC)	4.2	
Configuration	Single	

FEATURES

- Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)

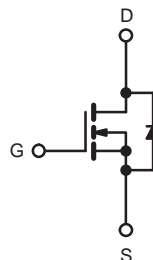
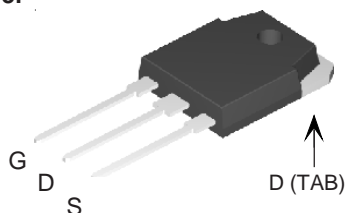


RoHS

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial

TO-3P



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	600	V
Gate-Source Voltage			V _{GS}	± 30	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	I _D	11	A
		T _C = 100 °C		9.7	
Pulsed Drain Current ^a			I _{DM}	50	
Linear Derating Factor				1.67/1.5/0.3	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	132	mJ
Maximum Power Dissipation			P _D	83/83/31	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope	T _J = 125 °C		dV/dt	50	V/ns
Reverse Diode dV/dt ^d		3.1			
Soldering Recommendations (Peak Temperature) ^c	for 10 s			300	°C

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 4.5$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/ μ s, starting $T_J = 25$ °C.

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	60	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.6	

SPECIFICATIONS ($T_J = 25\text{ °C}$, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	600	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C , $I_D = 1\text{ mA}$	-	0.65	-	V/°C
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	2	-	4	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
		$V_{GS} = \pm 30\text{ V}$	-	-	± 1	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 650\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	1	μA
		$V_{DS} = 520\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125\text{ °C}$	-	-	10	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 5\text{ A}$	-	0.38	-	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 30\text{ V}$, $I_D = 5\text{ A}$	-	16	-	S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}$, $V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$	-	680	-	pF
Output Capacitance	C_{oss}		-	140	-	
Reverse Transfer Capacitance	C_{rss}		-	5	-	
Effective Output Capacitance, Energy Related ^a	$C_{o(er)}$	$V_{DS} = 0\text{ V to } 520\text{ V}$, $V_{GS} = 0\text{ V}$	-	63	-	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$		-	113	-	
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$, $I_D = 5\text{ A}$, $V_{DS} = 520\text{ V}$	-	38	56	nC
Gate-Source Charge	Q_{gs}		-	4	-	
Gate-Drain Charge	Q_{gd}		-	4.5	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 520\text{ V}$, $I_D = 5\text{ A}$, $V_{GS} = 10\text{ V}$, $R_g = 9.1\text{ }\Omega$	-	13	25	ns
Rise Time	t_r		-	11	35	
Turn-Off Delay Time	$t_{d(off)}$		-	81	90	
Fall Time	t_f		-	25	40	
Gate Input Resistance	R_g	$f = 1\text{ MHz}$, open drain	-	3.5	-	Ω
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	11	A
Pulsed Diode Forward Current	I_{SM}		-	-	55	
Diode Forward Voltage	V_{SD}	$T_J = 25\text{ °C}$, $I_S = 5\text{ A}$, $V_{GS} = 0\text{ V}$	-	-	1.5	V
Reverse Recovery Time	t_{rr}	$T_J = 25\text{ °C}$, $I_F = I_S = 5\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}$, $V_R = 400\text{ V}$	-	270	-	ns
Reverse Recovery Charge	Q_{rr}		-	3.3	-	μC
Reverse Recovery Current	I_{RRM}		-	30	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
 b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



Fig. 7 - Typical Source-Drain Diode Forward Voltage

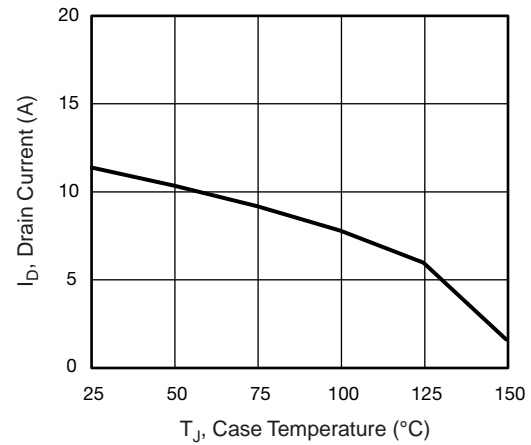


Fig. 9 - Maximum Drain Current vs. Case Temperature

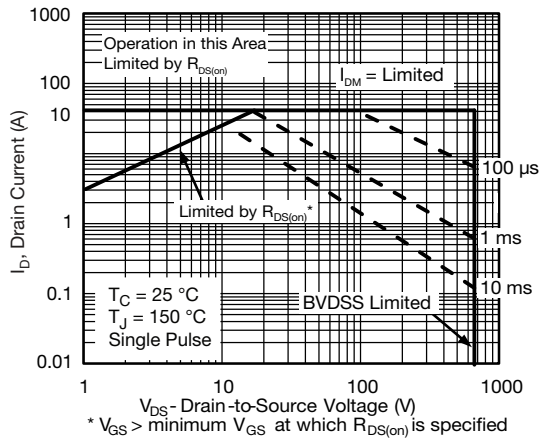


Fig. 8 - Maximum Safe Operating Area

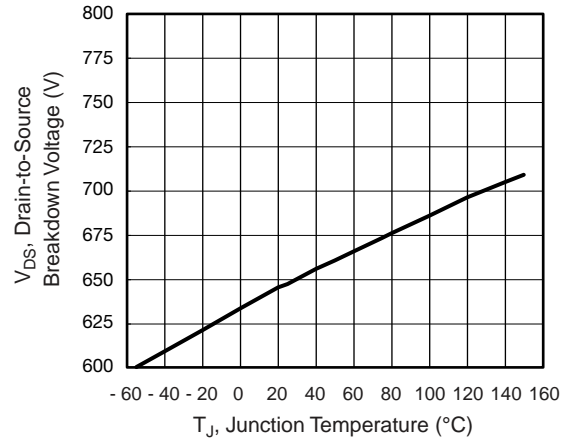


Fig. 10 - Temperature vs. Drain-to-Source Voltage

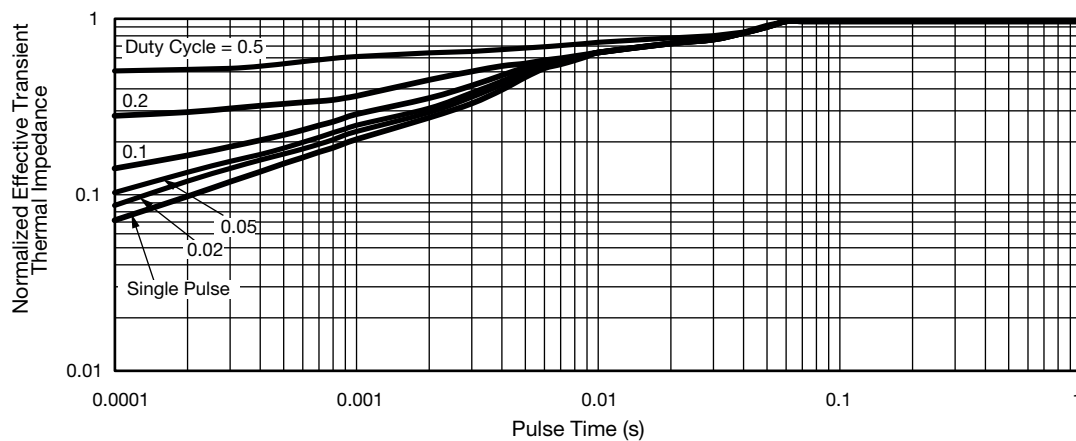


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



Fig. 12 - Switching Time Test Circuit



Fig. 16 - Basic Gate Charge Waveform



Fig. 13 - Switching Time Waveforms

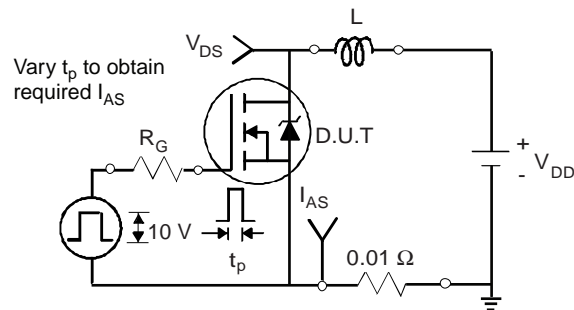


Fig. 14 - Unclamped Inductive Test Circuit

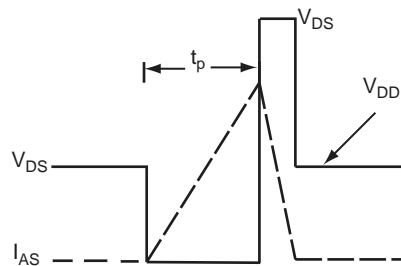
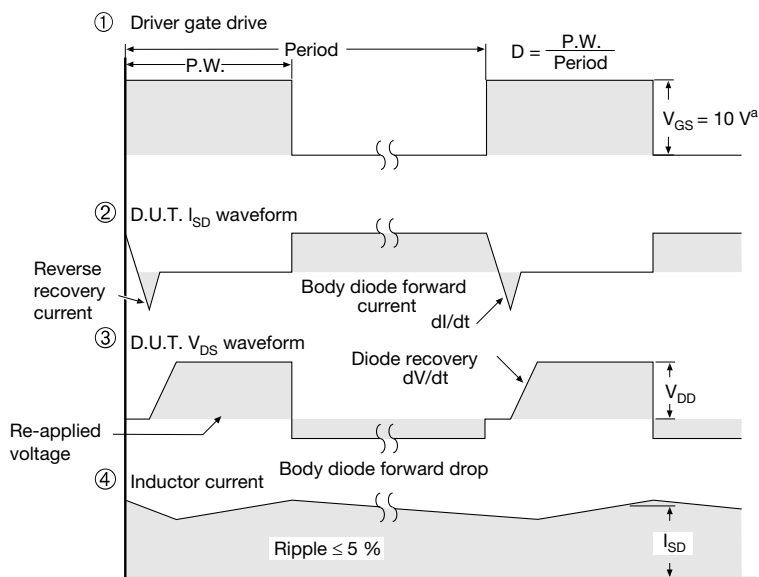


Fig. 15 - Unclamped Inductive Waveforms



Fig. 17 - Gate Charge Test Circuit

**Note**a. $V_{GS} = 5\text{ V}$ for logic level devices**Fig. 18 - For N-Channel**

Technical drawing of a 3-pin connector with dimensions in millimeters. The drawing includes a front view, a side view, and a detail view of the top.

Front View Dimensions:

- Overall width: 15.60 ± 0.20
- Width of top flange: 13.60 ± 0.20
- Width of top flange (inner): 9.60 ± 0.20
- Height of top flange: 3.80 ± 0.20
- Height of main body: 12.76 ± 0.20
- Height of main body (inner): 19.90 ± 0.20
- Overall height: 23.40 ± 0.20
- Height of pin base: 16.50 ± 0.30
- Pin diameter: $\varnothing 3.20 \pm 0.10$
- Pin spacing (typical): 5.45 TYP [5.45 ±0.30]
- Pin diameter (typical): 5.45 TYP [5.45 ±0.30]

Side View Dimensions:

- Overall height: 18.70 ± 0.20
- Width of top flange: 4.80 ± 0.20
- Width of top flange (inner): $1.50^{+0.15}_{-0.05}$
- Pin diameter: 1.40 ± 0.20
- Pin diameter (typical): $0.60^{+0.15}_{-0.05}$

Detail View Dimensions:

- Pin diameter: 2.00 ± 0.20
- Pin diameter (inner): 3.00 ± 0.20
- Pin diameter (outer): 1.00 ± 0.20

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